

IN THE CLAIMS:

Please amend the claims as follows:

1-13 (Cancelled)

14. (Currently Amended) A method of forming a contact ring, comprising:
providing a substrate;
depositing at least one a first conductive layer on the substrate, wherein said first conductive layer coats all surfaces of the substrate; and
depositing at least one a first insulative layer adjacent to the at least one a first conductive layer, on the substrate, wherein said first insulative layer coats all surfaces of the substrate.

15. (Original) The method of claim 14, further comprising electrically connecting a contact to at least one of the conductive layers.

16. (Original) The method of claim 14, wherein at least one of the conductive layers is of sufficient thickness such that after the depositing of at least one insulative layer, a compliant ridge is defined in the insulative layer.

17. (Original) The method of claim 16, further comprising electrically connecting a contact to at least one of the conductive layers, wherein the compliant ridge extends around the periphery of the contact.

18. (Original) A contact ring for providing electrical contact between a wafer and a power supply, comprising:
a conductive layer
an insulative layer deposited above the conductive layer;
a contact in electrical contact with the conductive layer and extending through the insulative layer to an external surface; and

a compliant ridge formed on the external surface, and extending about the periphery of the contact.

19. (Original) The contact ring of claim 18, wherein the insulative layer is a conformal layer, and the conductive layer is of a sufficient dimension to form the compliant ridge on the insulative layer.

20. (Currently Amended) The contact ridge ring of claim 18, wherein the compliant ridge is formed by an additional layer deposited on top of the insulative layer.

21-23 (Cancelled)

Please add the following new claims:

24. (New) A method for supplying electricity to a substrate, comprising:
forming a contact ring;
providing a plurality of contacts arranged on the contact ring and electrically coupled to a wiring network;
sensing the current applied to each of the plurality of contacts; and
controlling the current applied to each of the plurality of contacts in response to the current sensor.

25. (New) The method of claim 24, wherein the forming of the contact ring comprises:

providing a substrate;
depositing at least a first conductive layer on the substrate, wherein said first conductive layer coats all surfaces of the substrate; and

depositing at least a first insulative layer adjacent to the at least a first conductive layer, on the substrate, wherein said first insulative layer coats all surfaces of the substrate.

26. (New) The method of claim 24, wherein the controlling the current further comprises balancing the current applied to each of the plurality of contacts.

27. (New) The method of claim 24, wherein the controlling the current further comprises varying the resistance of a conductor that supplies the current to the contact.

28. (New) The method of claim 24, wherein the controlling the current further comprises varying the current level applied to a conductor that supplies the current to the contact.